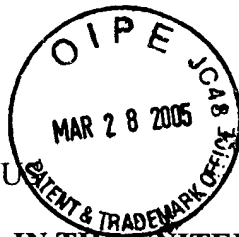


UNIU79.014AU



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE


Applicant : Matsumura, et al.  
Appl. No. : 10/678,855  
Filed : October 3, 2003  
For : DICING/DIE-BONDING FILM,  
METHOD OF FIXING CHIPPED  
WORK AND SEMICONDUCTOR  
DEVICE  
Examiner : Laura M Schillinger  
Group Art Unit : 2813

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

March 24, 2005

(Date)

  
Katsuhiro Arai, Reg. No. 43,315

AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed December 28, 2004, please reconsider the present application in light of the following amendments and comments.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.